

ABSTRACT

A substrate polishing device includes a turntable having a first adhesive surface, and a polishing pad having a second adhesive surface adhesively fixed to the first adhesive surface. An adhesive region and a first separation assistance region are provided between the first adhesive surface and the second adhesive surface. The first adhesive surface and the second adhesive surface are adhered to each other in the adhesive region. An adhesive force acting between the first adhesive surface and the second adhesive surface in the first separation assistance region is smaller than an adhesive force acting between the first adhesive surface and the second adhesive surface in the adhesive region. The first separation assistance region is positioned on an outer circumferential portion of the polishing pad.

Figure 1